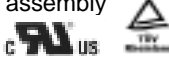




LP-SM130

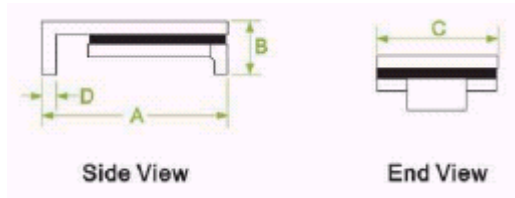
Features

- Small size of 1812
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV

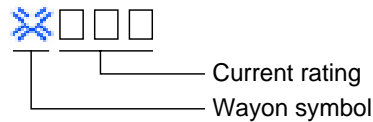


Product Dimensions (mm)

Part number	A Max	B Max	C Max	D Max
LP-SM130	9.50	3.00	6.71	0.70



Part Marking System

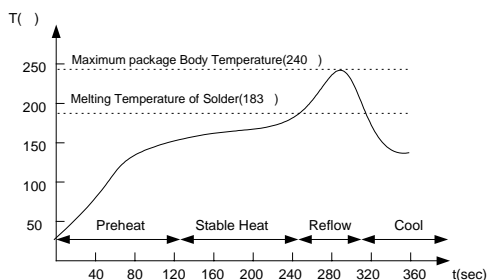
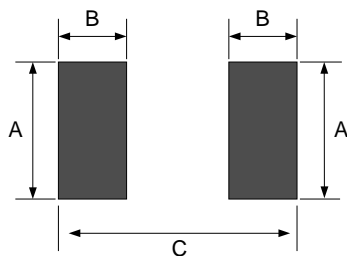


Electrical Characteristics

Part number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} Current(A) Time(S)	Pd_{typ} (W)	R_{min} ()	R_{1max} ()
LP-SM130	1.30	2.60	33	40	8.0 4.0	2.1	0.080	0.280

I_H =Hold current: maximum current at which the device will not trip at 25 still air.
 I_T =Trip current: minimum current at which the device will always trip at 25 still air.
 V_{max} =Maximum voltage device can withstand without damage at rated current.
 I_{max} =Maximum fault current device can withstand without damage at rated voltage.
 T_{trip} =Maximum time to trip(s) at assigned current.
 Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min} =Minimum device resistance at 25 prior to tripping.
 R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-SM130	4.6	2.3	10.7

- * Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.
- * Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.